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- (71) Applicant (for all designated States except US): **SHOWA DENKO K.K.** [JP/JP]; 13-9, Shibadaimon 1-chome, Minato-ku, Tokyo, 1058518 (JP).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **MORINAKA, Katsutoshi** [JP/JP]; c/o SHOWA DENKO K.K., 111, Aza-Nagayachi, Ooaza-Higashinagahara, Kawahigashi-machi, Kawanuma-gun, Fukushima, 9693431 (JP). **HOSHI, Kazuyoshi** [JP/JP]; c/o SHOWA DENKO K.K., 111, Aza-Nagayachi, Ooaza-Higashinagahara, Kawahigashi-machi, Kawanuma-gun, Fukushima, 9693431 (JP).
- (74) Agent: **SUZUKI, Shunichiro**; S.SUZUKI & ASSOCIATES, Gotanda Yamazaki Bldg. 6F, 13-6, Nishigotanda 7-chome, Shinagawa-ku, Tokyo, 1410031 (JP).
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(54) Title: PROCESS FOR PREPARING HIGH PURITY (METH)ACRYLOYLOXYALKYL ISOCYANATE

(57) Abstract: A process for preparing a high purity (meth)acryloyloxyalkyl isocyanate having a very small hydrolyzable chlorine content is provided. The high purity (meth)acryloyloxyalkyl isocyanate is prepared by subjecting a hydrolyzable chlorine containing (meth)acryloyloxyalkyl isocyanate to mixing treatment with an epoxy compound and an amine at a temperature of from 110 to 160°C to prepare a mixture; and preparing a high purity (meth)acryloyloxyalkyl isocyanate from the resulting mixture with distillation. In particular, it is possible to effectively prevent (meth)acryloyloxyalkyl isocyanate from polymerization during the distillation by adding a polymerization inhibitor such as phenothiazine and the like.

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